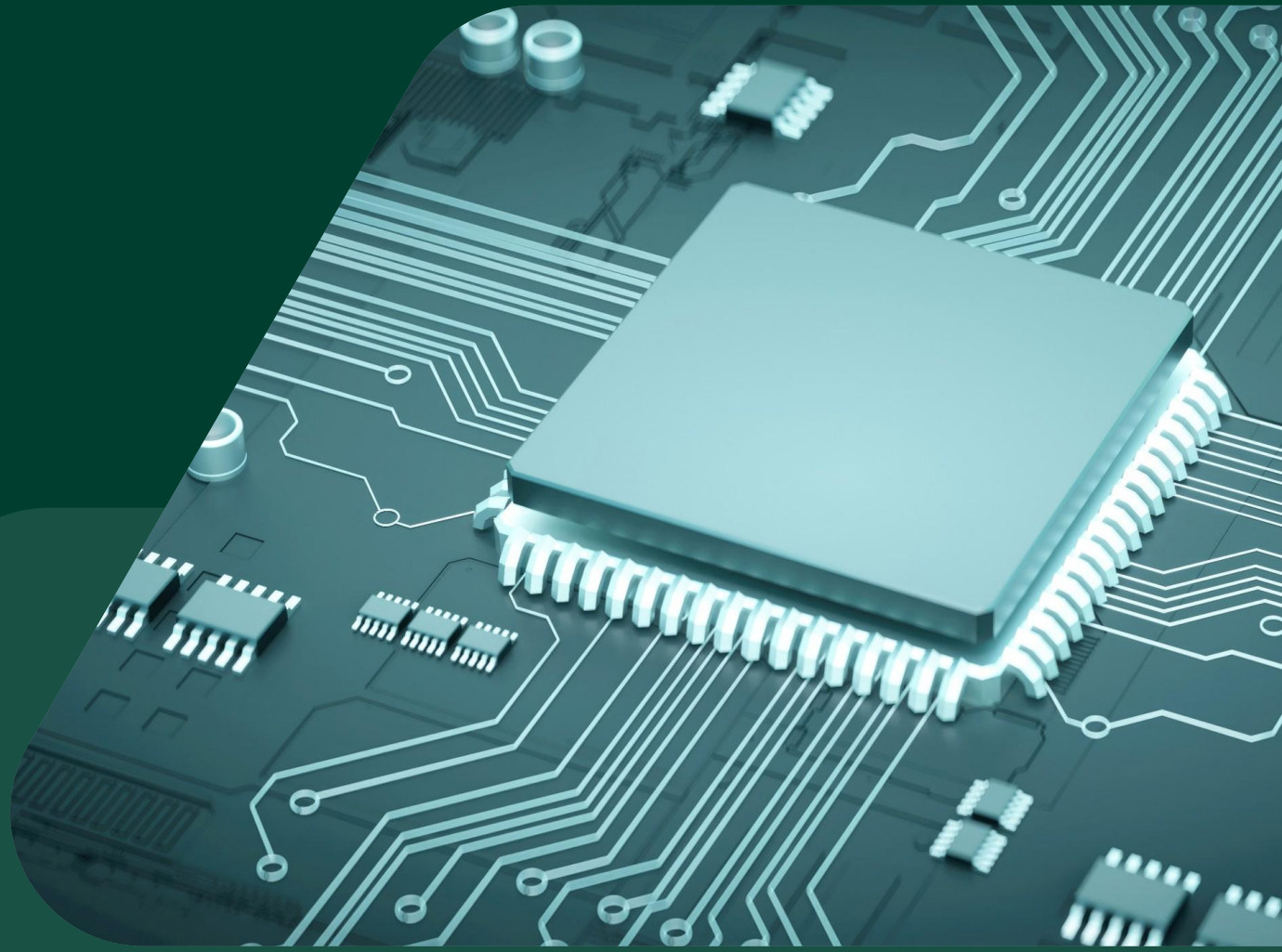
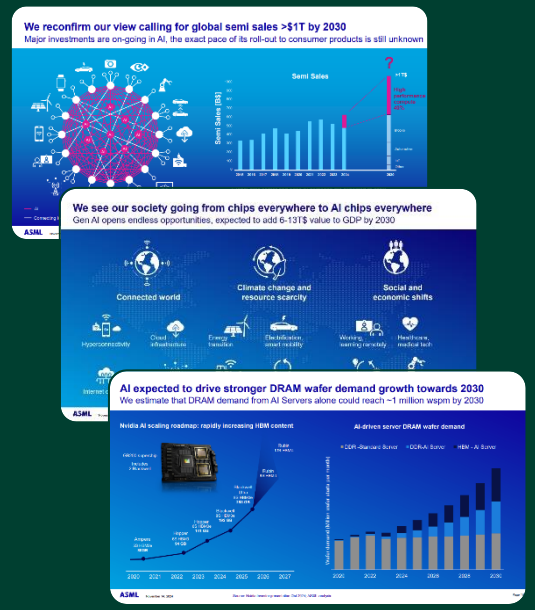
Market Overview & Ambition 2030

(Burkhardt Frick)

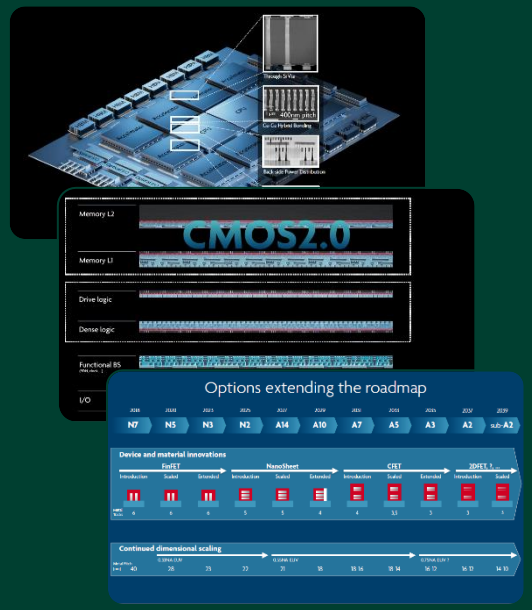


Our strategic growth plan builds on in-depth market research and industry investigations

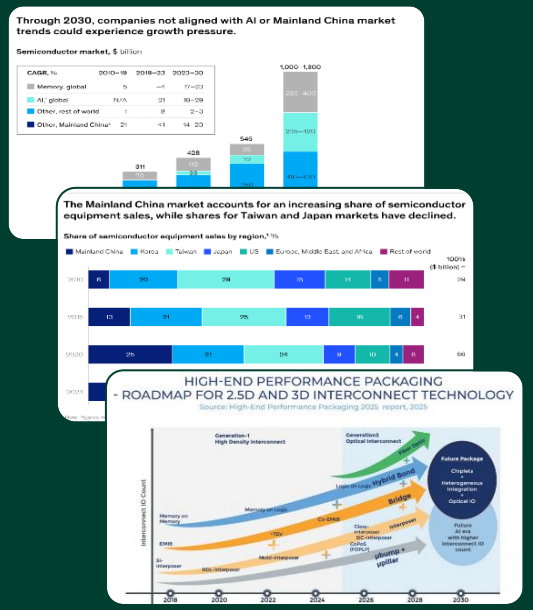
1. **Insights from industry peers**
2. **Development roadmap of leading research institutes**
3. **Studies by global consulting and research leaders**
4. **Application & roadmap discussions with industry leaders**



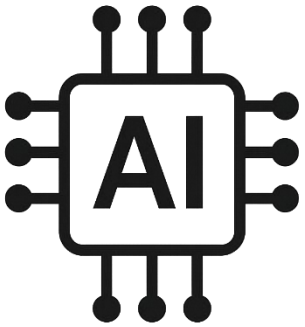
Source: ASML



Source: imec

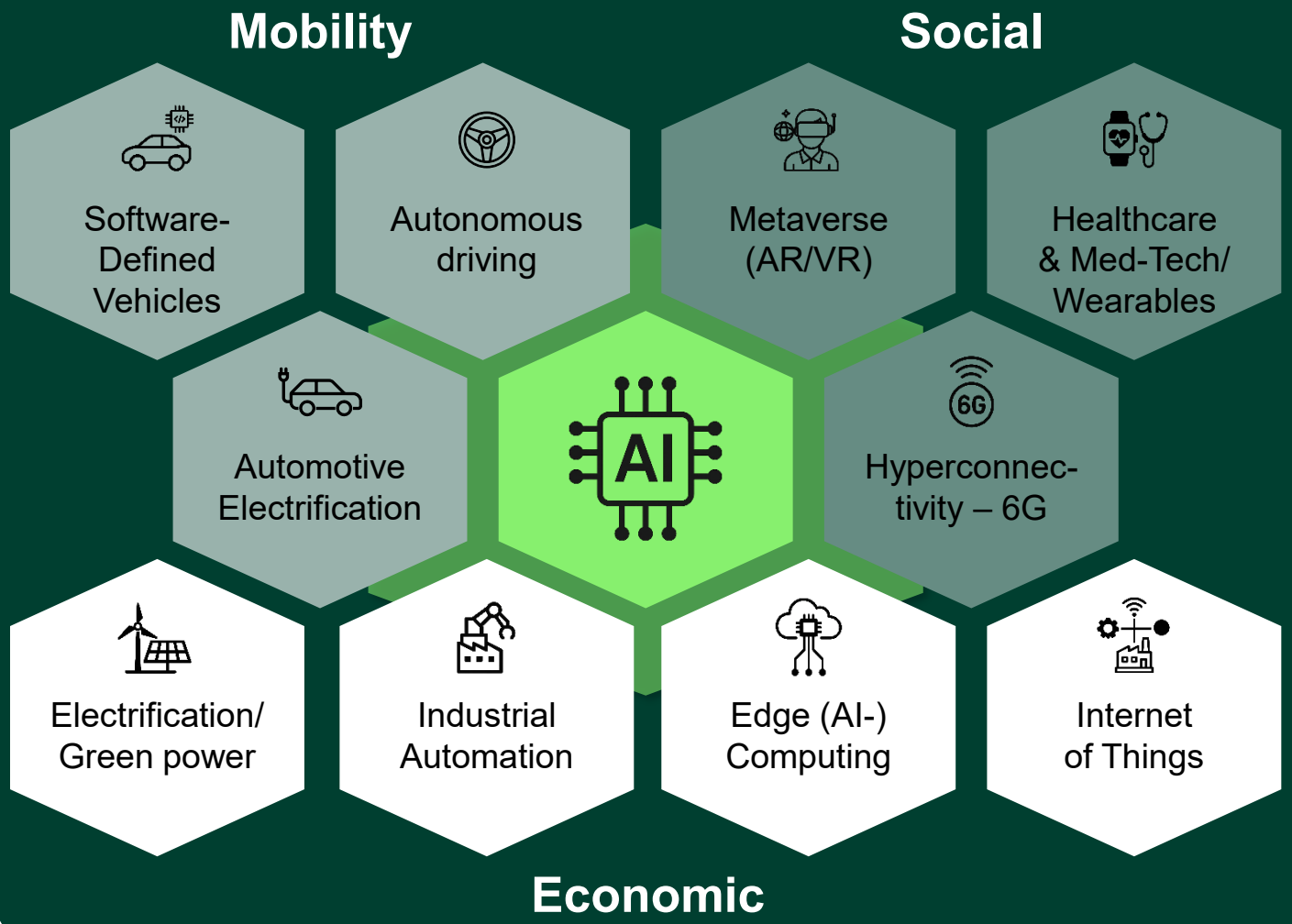


Source: McKinsey and Company, Yole



Today's tech trends, accelerated by AI, are built on semiconductors

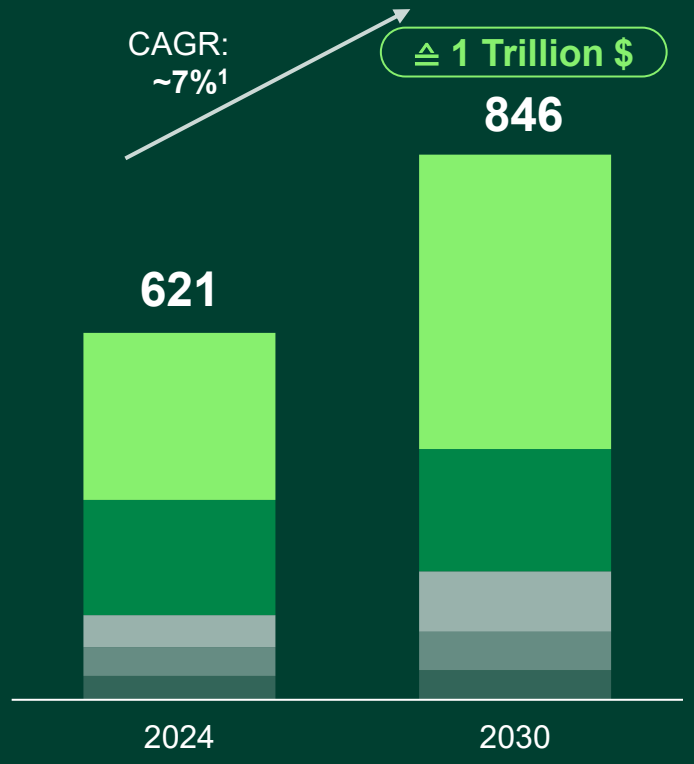
Fueling rapid growth across the semiconductor ecosystem



Trend Selection – not exhaustive

AI-led secular trends are driving semiconductors toward a $1 trillion market by 2030

Semiconductor device revenue forecast (€bn) & key growth driver



Market segment	Growth-drivers	
Computing & Data Storage	**AI** (Generative-, Agentic-, Physical-AI)	Key growth driver
	Autonomous driving	
	Industrial Automation / Internet of Things	
	Metaverse (AR/VR)	
Communications	Hyperconnectivity – 6G	
Automotive	Software-Defined Vehicles / Autonom. driving	
	Automotive Electrification	
Industrial	Industrial Automation / Internet of Things	
	Electrification / Green power generation	
Consumer	Metaverse (AR/VR)	
	Healthcare Wearables	

[1] Based on USD values
Source: SUSS Research; market size based on Yole (2025); Note: USD/EUR forward exchange rate = 1.18, USD/EUR 2024 exchange rate = 1.08, Trend Selection – not exhaustive

Rising application requirements are blurring the lines between Frontend & Backend territories – addressed in our Business Unit strategy

SUSS

Frontend

Node size mitigation: Moore's Law continues with nodes shrinking toward Ångström era

Backend

Advanced Packaging: evolution & broad adoption of heterogeneous chiplet technology

Higher accuracy & cleanliness driving customer demands closer to frontend standards

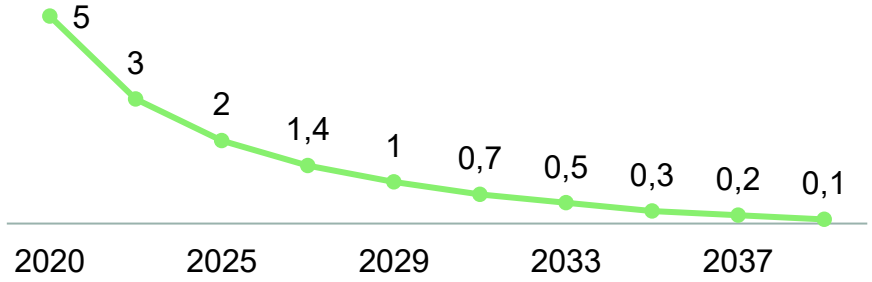
Efficient & green processes:
Growing customer demand for reduced material usage and environmentally sustainable materials

Photomask Solutions	**Photomask Cleaning, Bake & Develop**	**Wafer Cleaning**
Advanced Backend Solutions		**Bonding, Coating & Imaging**

Node size mitigation | Moore's Law continues, yet decelerates, Mid-end nodes maintain high revenue share – we serve a broad spectrum

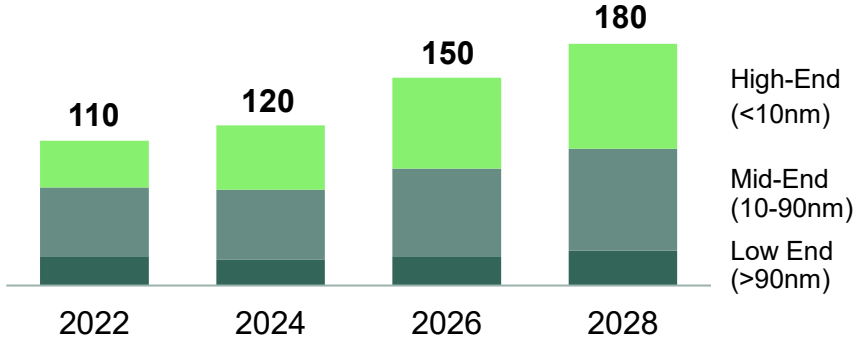
Moore's Law will continue; despite slow-down in geometrical scaling

Node size (leading-edge) in nm
Roadmap ASML



High-End nodes drive revenue growth, Mid- & Low-End maintain high share

Foundry revenue per node (€ bn)



Source: ASML, Gartner; Note: USD/EUR forward exchange rate = 1.18

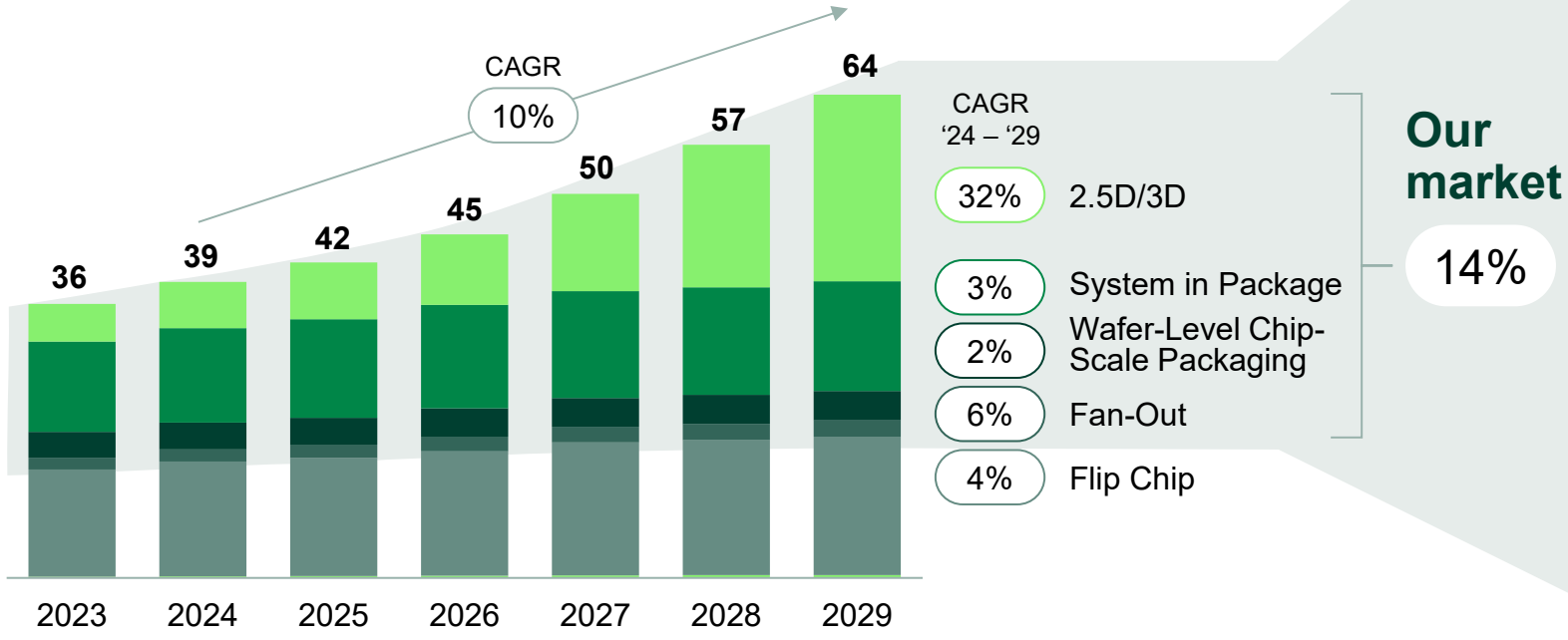
With our photomask portfolio we address the semiconductor node landscape – from mature to leading-edge nodes

- **<2 nm** › **Mask Track *Smart***
- **2–10 nm** › **MaskTrack X**
- **14–32 nm** › **MaskTrack Pro**
- **38–90 nm** › **ASx 9500**

Advanced Packaging | Strong growth ahead – largely fueled by 2.5D and 3D packaging

As demand for high-performance computing rises, the **value in Advanced Packaging is shifting** toward high-end technologies

Advanced Packaging forecast [Million Wafer/Year]



XX% CAGR '24 – '29

Source: Yole (2024)

Interconnection of chips, wafers, and interposers (e.g., Redistribution Layers, Through-Interposer Via, Micro Bumps)

- Patterning with our Lithography equipment: (Coater & Developer, Exposure equipment)

Structural support for thin elements

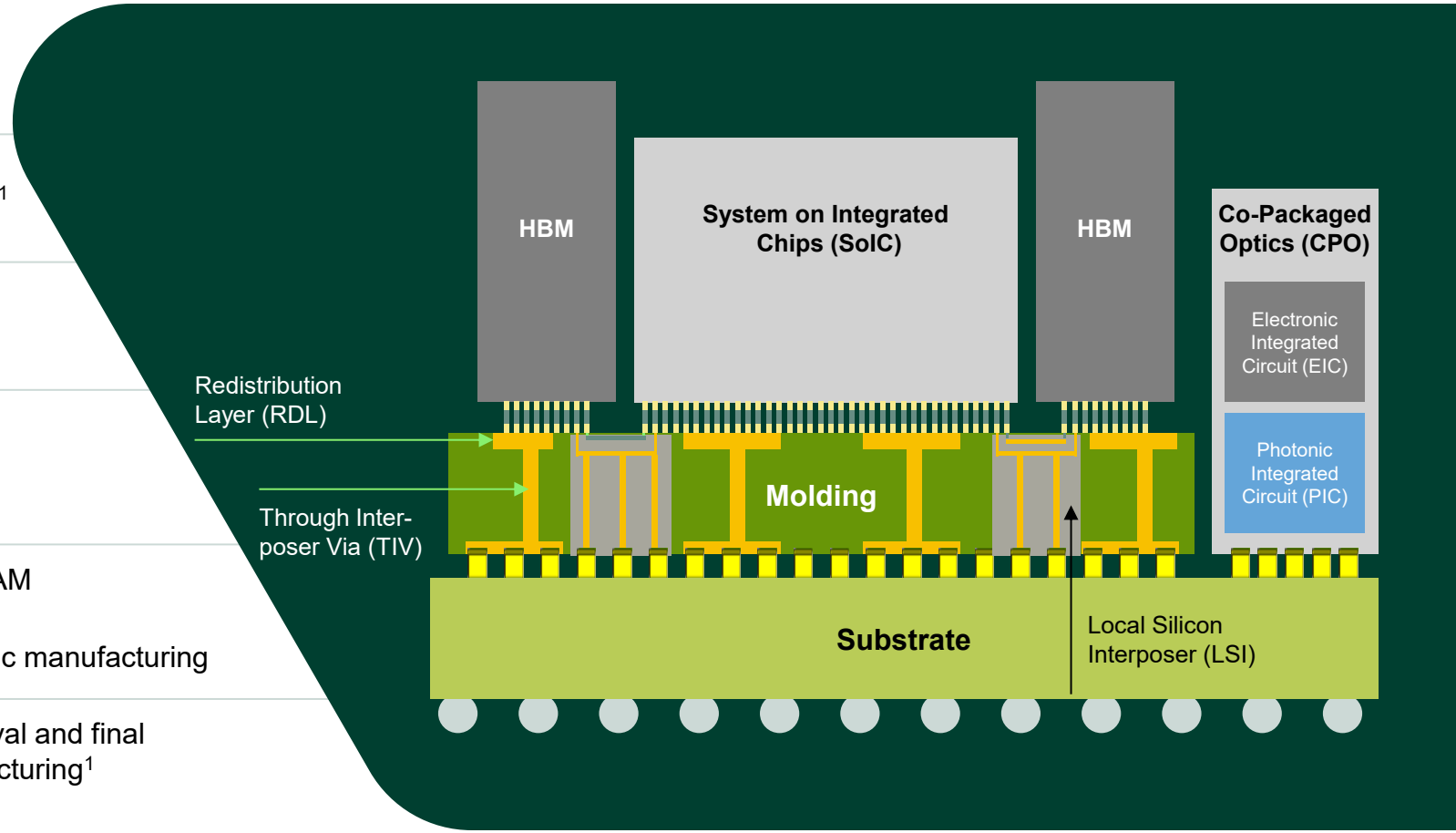
- Temporary bonding on carrier wafer with our temporary bonding/de-bonding equipment

Mounting dies onto other dies or interposers

- Interposer stacking and die attach/ stacking with our permanent bonding equipment (incl. Hybrid Bonding)

2.5/3D Chiplet Technology | SUSS well positioned to benefit from the strong momentum in 2.5D and 3D evolution

Temporary Bonding	• **HBM:** Structural support during thinning
Hybrid Bonding	• **HBM:** Stacking of DRAMs[1] • **CPO:** Stacking of PIC & EIC[1] • **SoIC:** E.g., Logic-on-Logic[1]
Inkjet-/ Spin Coating	• **TIV:** Lithography • **RDL:** Lithography[1]
UV-Scanner (Exposure)	• **TIV:** Lithography • **RDL:** Lithography[1]
Photomask Cleaning (Frontend)	• **HBM:** Mask Cleaning in DRAM manufacturing • **SoIC:** Mask Cleaning in Logic manufacturing
Wafer Cleaning	• **HBM:** Critical material removal and final cleaning in Backend manufacturing[1]



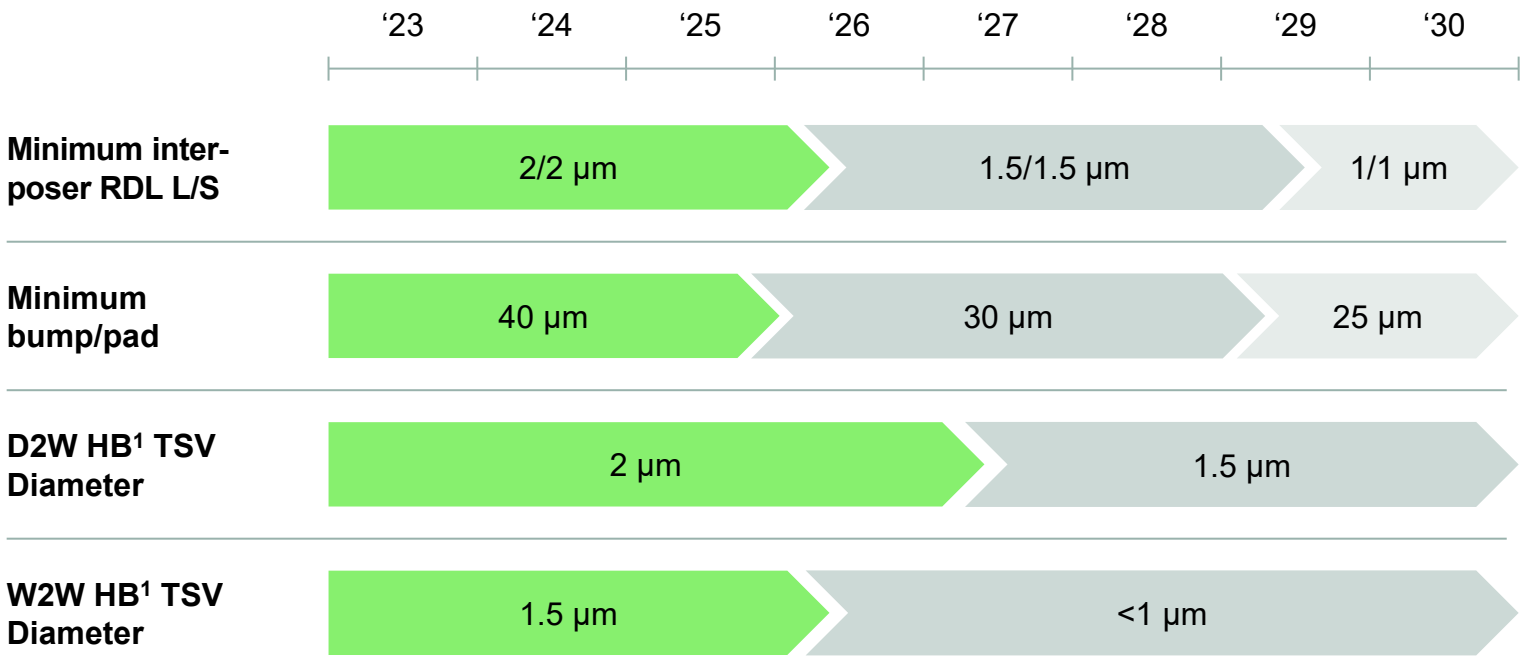
[1] Potential future use case

BU Advanced Backend Solutions

BU Photomask Solutions

Higher accuracy & cleanliness in Backend | Rising performance demands push accuracy & cleanliness in Advanced Packaging toward Frontend standards

Evolution of precision requirements in Advanced Packaging



[1] Hybrid Bonding | Source: Yole (2025)

Ongoing equipment enhancements & roll-out of new processes & equipment required

- **Hybrid Bonding:** D2W/W2W Hybrid Bonder released (2025) and set for continuous upgrades
- **Temp. Bonding/De-Bonding:** Release of Next-Gen equipment in 2027 for ever-thinner wafers
- **Exposure:** Release of Next-Gen UV-Scanner in 2027 with improved Overlay accuracy & L/S

Beyond higher cleanroom demands, enhanced wafer cleaning becomes essential

GreenTrack: Also addressing Advanced Packaging steps such as TSV and Plasma Activation

Efficient & green processes | Rising demand for ESG-compliant equipment

Zero emissions growth by 2025, and achieving **net-zero emission** across the value chain by **2050.**

TSMC continuously **minimizes resource consumption at the source,** adjusts raw material usage parameters & technical solutions for process improvements, & collaborates with suppliers to achieve material optimization & minimization.

42% absolute reduction in operational emissions by 2030 (vs. 2020 baseline) and net-zero emissions by 2050.

Amkor commits to reaching absolute **Scope 1 and 2 green-house gas emissions by 55% by 2033 from a 2022** base year.

Net-zero greenhouse gas emissions **across the value chain by 2050.**

Product carbon footprint reduction from Cradle to Grave

We work hand-in-hand with customers to reduce carbon footprint across all life-cycle stages

Material-Efficient Processes

We have developed and keep developing processes & equipment to cut harmful material use – E.g.

- **Inkjet** saves >50% coating material,
- **Pellicle Glue Buster** cuts acid use up to 1,000x (mask cleaning)

Utilization of Green Materials

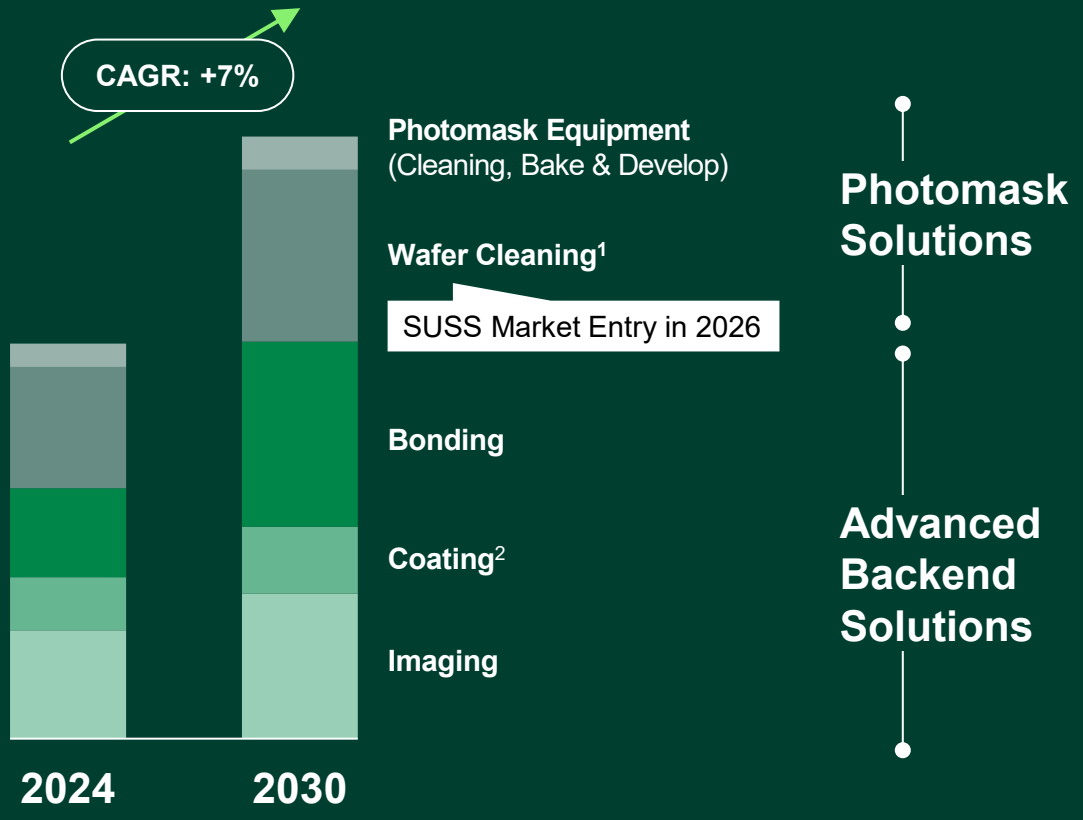
We have developed and keep developing processes & equipment to replace harmful materials – E.g. wafer cleaning

- **Replacement of harmful petroleum-based solvents** with innovative water-based fluids
- **Decomposition of organic materials** by UV-light – Leaving no harmful residues

Source: Company Webpage & Annual Reports

Serviceable market is expected to grow by ~7% per annum through 2030

Serviceable Available Market (Revenue in €M)



[1] MEMS, Power, CIS & Advanced Packaging market reflected; [2] Only Backend Coating market; Inkjet: Upside from expanding into additive manufacturing not reflected | Source: SUSS Research, primarily based on Yole

Photomask Equipment

- **High-End mask market leading growth**
- Mid-End mask market growing mid-to high single digits annually

Wafer Cleaning

- **Market entry with MEMS, Power & CMOS Image Sensors;** Expansion into Advanced Packaging with 300 mm tool planned (tool launch in 2027)
- Memory – future upside (not in market size reflected)

Bonding

- **Temporary Bonding** will **continue to grow** especially driven by high demand for AI
- **Hybrid Bonding with strong growth** ahead driven by advanced Logic & Memory

Coating

- **Advanced Packaging drives growth** in Backend Coating segment
- **Inkjet offers upside beyond traditional coating**, expanding into additive manufacturing

Imaging

- **Advanced Packaging fuels growth;** larger reticle-size dies supports adoption of full-field projection scanning

SUSS position in selected markets

#1 Market Leader

- ~100% Full-field projection UV-Scanning
- >80% Photomask Cleaning (High-end)
- ~65% Photomask Bake & Develop
- ~60% Mask Aligner
- ~45% Temporary Bonding / Debonding

Market share[1]

#2 First Follower

- ~20% Photomask Cleaning (Mid-end)
- ~15% Spin Coating (excl. Frontend)
- ~10% Permanent Bonding

Market share[1]

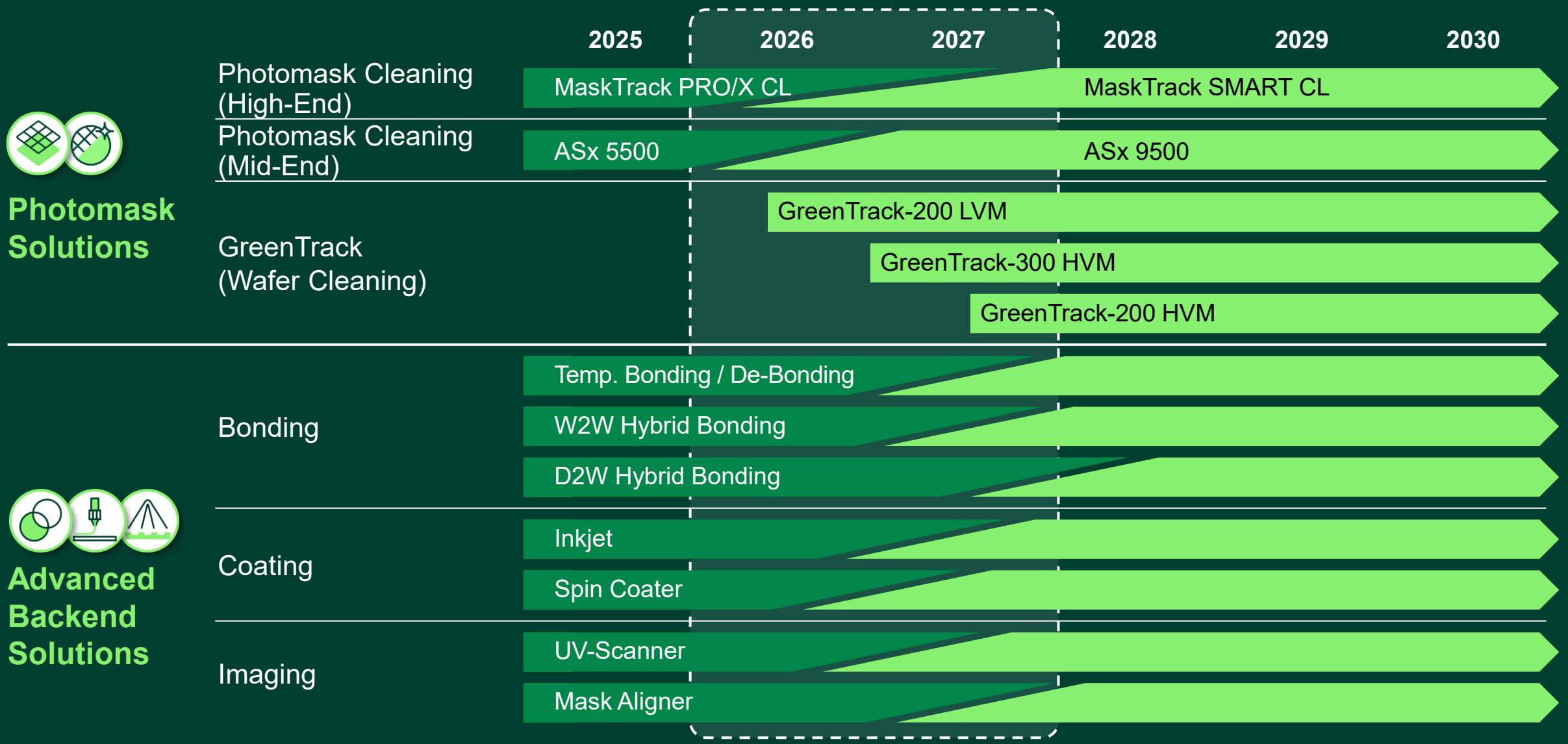
New Market Entry

- - Hybrid Bonding
- - Inkjet
- - Wafer Cleaning

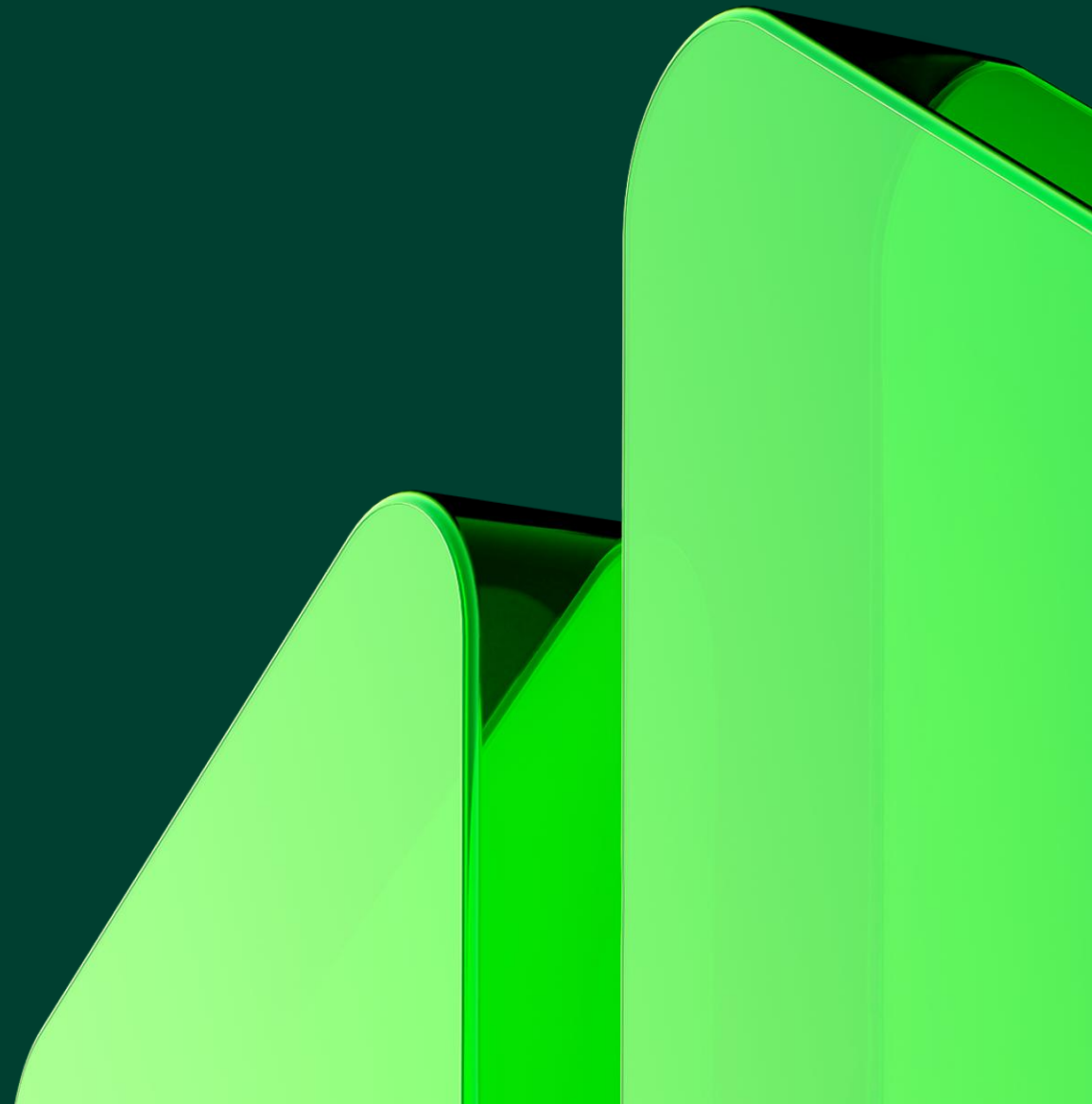
Market share[1]

[1] Source: SUSS Research, based on Yole

Upcoming new product introductions – initiating next growth phase



Growing Innovation



SUSS long term ambitions for 2030

€ 750 – 900 m

Sales
SUSS Ambition 2030

~ 9 –13% annual sales growth
compared to 2025e

43 – 45%

Gross profit margin
SUSS Ambition 2030

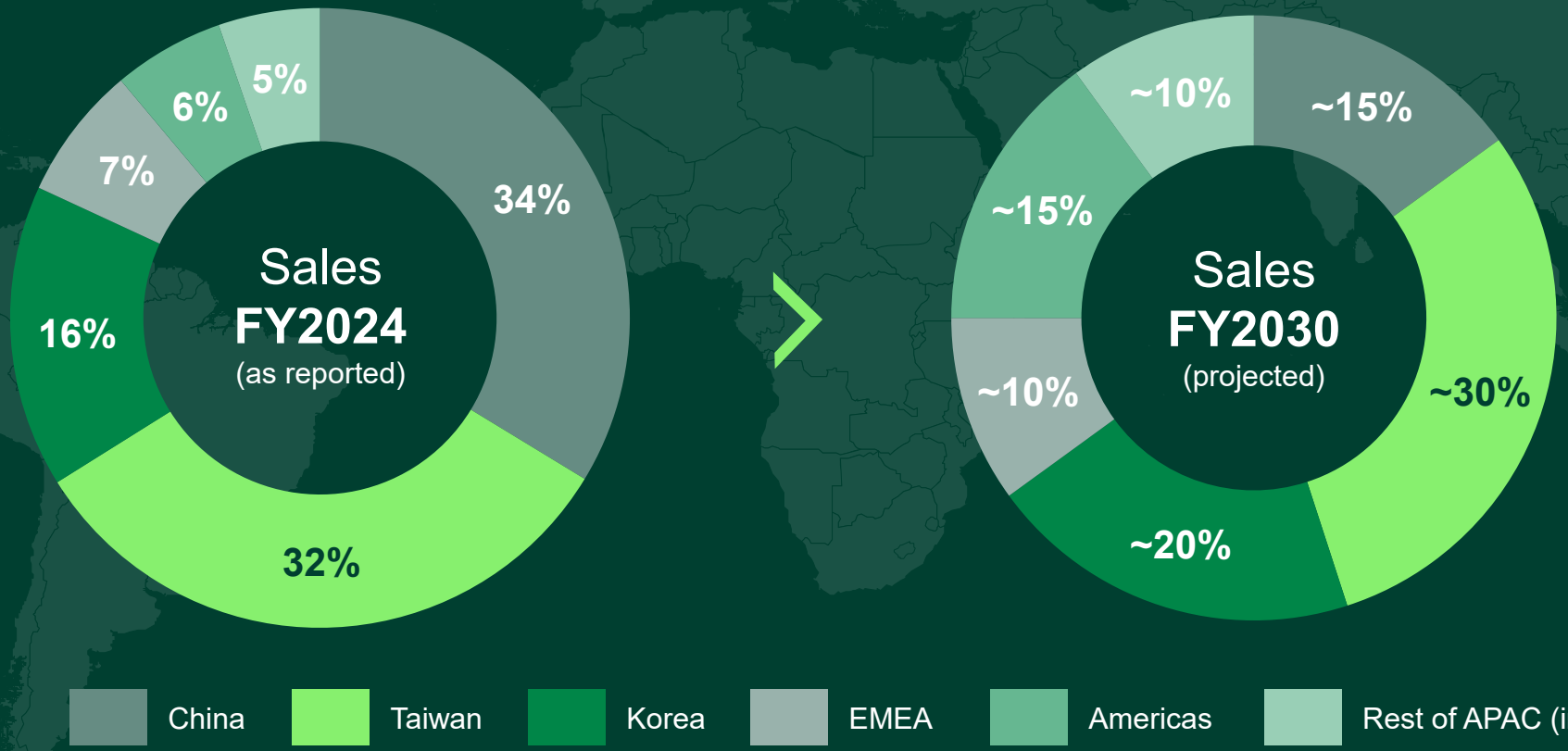
+ ~8%-points GP margin
expansion compared to 2025e

20 – 22%

EBIT margin
SUSS Ambition 2030

+ ~9%-points EBIT margin
expansion compared to 2025e

More diversified regional growth – with normalizing China share



SUSS – a valued partner in the semi ecosystem – Working alongside leading chip companies, as well as key research and industrial partners

We have expanded our global standing

and have become a valued part of the semi ecosystem.

Our key success factors are:

- Focusing on market leaders
- Engaging into commercial and technology partnerships
- Creating customer intimacy through joint process development and key account management
- Local presence with highly qualified customer service and application support

Foundries and OSATs	Integrated Device Manufacturers (IDMs)	Technology and material partners	Academia, consortia and institutes
TSMC	Micron	SET	imec
Amkor Technology	SAMSUNG	Brewer Science	CEA leti
ASE	SK hynix	Nissan Chemical Corporation	semi[1]
	intel.	Shin-Etsu	Fraunhofer
	Infineon	EPSON	TUM
	ST	micro resist technology	KIT
	onsemi	CORNING	Texas Institute for Electronics
	Wolfspeed	SCHOTT	bridg
	Texas Instruments		Georgia Tech

[1] 3DIC Advanced Manufacturing Alliance

Strategic focus on Customer Service to grow revenue and margin

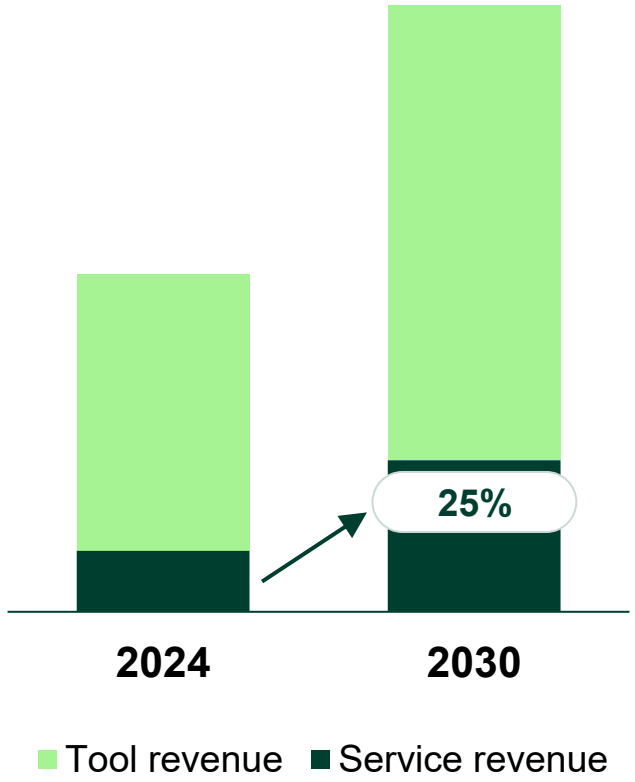
We are increasing our **sales share in service business** from **18% to 25%**, which will lead to revenue growth in services to between **€190m and €225m**.

Customer Satisfaction

Well-trained service personnel trained in our local training centers

Proximity

A service portfolio with uptime commitments and cooperative partnership business models



Service Portfolio

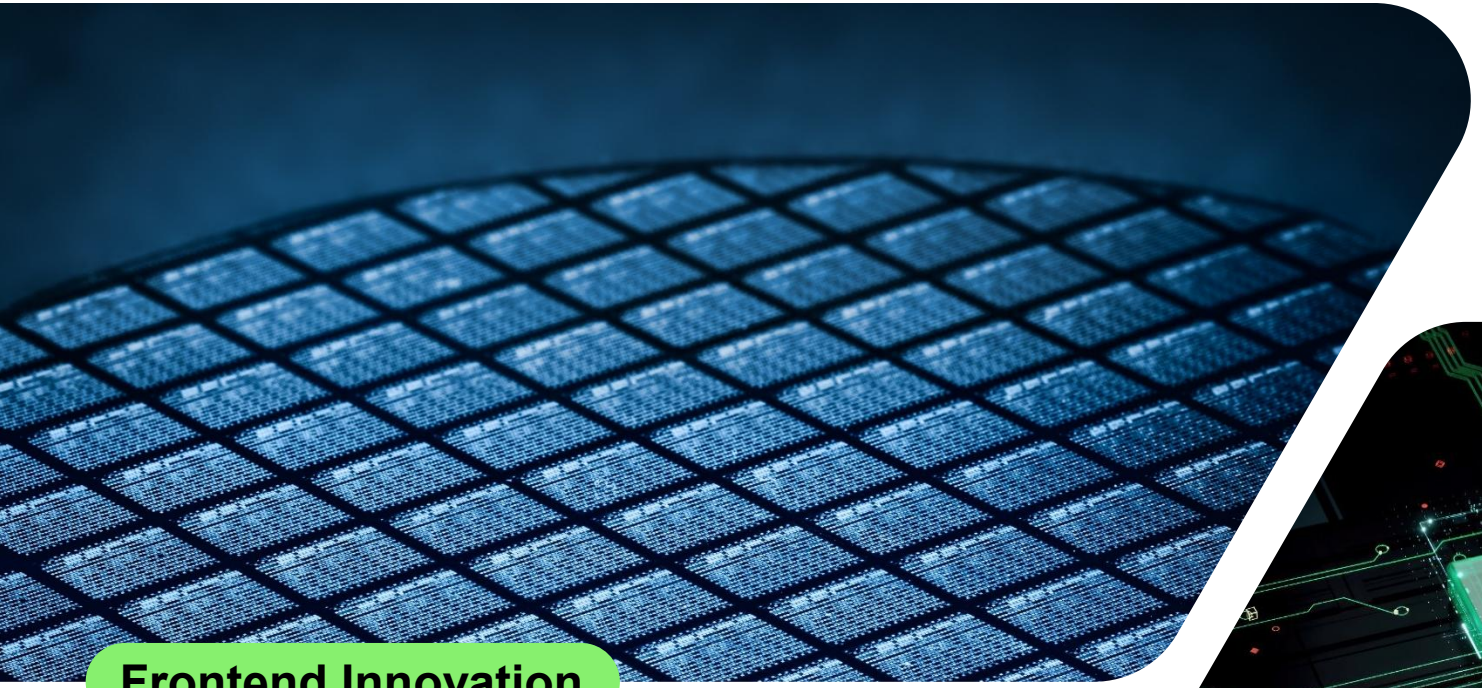
Customer centric service portfolio enabling our customers to concentrate on their targets/business

Service innovations

In collaboration with our customers, we develop innovative services, such as predictive maintenance.

It is our target to achieve a **Gross Profit margin** of over **50%** in our service business.

We are fully committed to drive the next chapter of innovation and growth in Frontend (Moore's Law) and Backend (More than Moore)

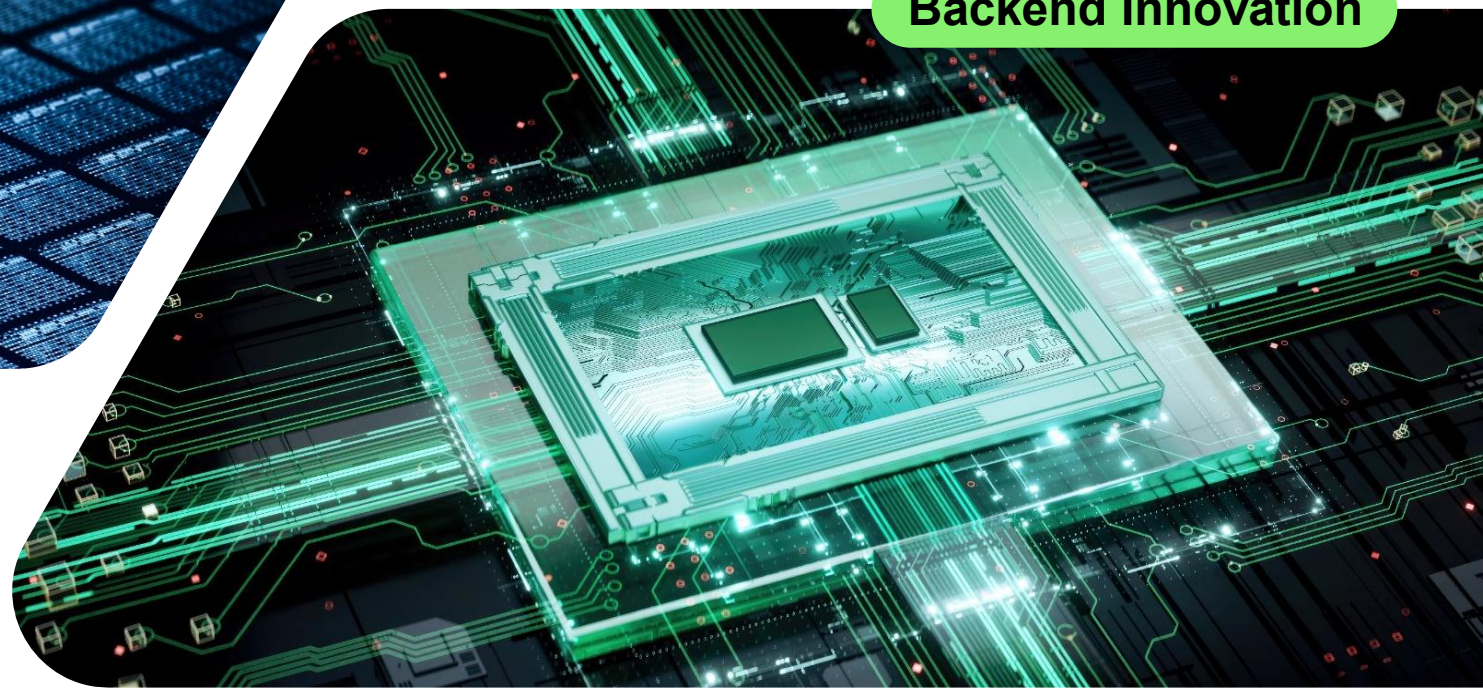


Frontend Innovation

Striving for the next technology node

Heterogeneous integration creates new multi-chip modules

Backend Innovation



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